L Number	Hits	Search Text	DB	Time stamp
13	1	6396699.pn.	USPAT;	2004/05/14 10:28
		·	US-PGPUB	
17	2	6437240.URPN.	USPAT	2004/05/14 10:46
18	57	("2734154"   "4034468"   "4034469"   "4233645"	USPAT	2004/05/14 10:53
		"4254431"   "4299715"   "4323914"   "4398975"		
		"4435611"   "4466483"   "4473113"   "4607277"		
		"4806111"   "4915167"   "4966142"   "5011787"		
		"5031308"   "5037312"   "5056706"   "5071787"		
		"5074947"   "5086558"   "5097387"   "5131582"		
i		"5148141"   "5148265"   "5148266"   "5164566"     "5170930"   "5196371"   "5198189"   "5223747"		
		3170930   3190371   3190109   3223747     "5237130"   "5323265"   "5323294"   "5328087"		
		"5367435"   "5410449"   "5445308"   "5455390"		
		"5459352"   "5542602"   "5553769"   "5557501"		
		"5561590"   "5572404"   "5611884"   "5651179"		
		"5658831"   "5688721"   "5720100"   "5745344"		
		"5808874"   "5819406"   "5920125"   "5975408"		
		"6000127").PN.		
22	3	5777385.URPN.	USPAT	2004/05/14 10:59
23	7	("4149310"   "4561040"   "5291064"   "5378924"	USPAT	2004/05/14 11:05
		"5525834"   "5583073"   "5614766").PN.		
26	2	("5592735"   "5777385").PN.	USPAT	2004/05/14 11:06
27	1	6162659.URPN.	USPAT	2004/05/14 11:07
28	4074	438/108.ccls. 438/122.ccls. 438/124.ccls. 438/127.ccls.	USPAT;	2004/05/14 11:15
	225	438/612.ccls. 438/613.ccls. 438/615.ccls.	US-PGPUB	2004/05/44 44:24
30	986	(438/108.ccls. 438/122.ccls. 438/124.ccls. 438/127.ccls.	USPAT;	2004/05/14 11:21
1		438/612.ccls. 438/613.ccls. 438/615.ccls.) and (bump\$5 ball	US-PGPUB	
		protrusion solder ubm underbump pad contact) and (heat near (sink spreader dissipat\$6))		
31	473	(438/108.ccls. 438/122.ccls. 438/124.ccls. 438/127.ccls.	USPAT;	2004/05/14 11:25
31	7/3	438/612.ccls. 438/613.ccls. 438/615.ccls.) and (solder adj	US-PGPUB	2001/05/11/11:25
		(bump\$5 ball protrusion)) and (heat near (sink spreader	0510.05	
		dissipat\$6)) and ((flip ic circuit semiconductor) adj (chip die		
		dice))		
33	395	((438/108.ccls. 438/122.ccls. 438/124.ccls. 438/127.ccls.	USPAT;	2004/05/14 12:41
		438/612.ccls. 438/613.ccls. 438/615.ccls.) and (solder adj	US-PGPUB	
		(bump\$5 ball protrusion)) and (heat near (sink spreader		
		dissipat\$6)) and ((flip ic circuit semiconductor) adj (chip die		
ŀ		dice))) and ((substrate carrier module) with (pad contact		
		electrode ubm underbump))		2004/05/44 45:06
34	175	(solder adj (bump\$5 ball protrusion)) same (heat near (sink	USPAT;	2004/05/14 15:06
		spreader dissipat\$6)) same ((flip ic circuit semiconductor)	US-PGPUB	
		adj (chip die dice)) same ((substrate carrier module) with (pad contact electrode ubm underbump)) same (align\$6		
ļ	•	reflow\$6 attach\$6 underfill encapsulat\$6 join\$6 bond\$6)		
36	1	6507104.URPN.	USPAT	2004/05/14 14:35
37	13	("5522667"   "5619070"   "5726079"   "5920120"	USPAT	2004/05/14 14:36
37	13	"5939783"   "5977626"   "6117705"   "6150724"	00.711	2001,00,1111.50
		"6191360"   "6218730"   "6255143"   "6265771"		
		"6271058").PN.		
35	66	(solder adj (bump\$5 ball protrusion)) and (heat near (sink	EPO; JPO;	2004/05/14 14:54
		spreader dissipat\$6)) and ((flip ic circuit semiconductor) adj	DERWENT;	
		(chip die dice)) and ((substrate carrier module) with (pad	IBM_TDB	
		contact electrode ubm underbump)) and (align\$6 reflow\$6	[	
		attach\$6 underfill encapsulat\$6 join\$6 bond\$6)		
38	19	((bump\$5 ball protrusion) near2 (heat near (sink spreader	USPAT;	2004/05/14 15:07
		dissipat\$6))) same ((flip ic circuit semiconductor) adj (chip	US-PGPUB	
		die dice)) same ((substrate carrier module) with (pad	1	
		contact electrode ubm underbump)) same (align\$6 reflow\$6		
40	200	attach\$6 underfill encapsulat\$6 join\$6 bond\$6) (bump\$5 ball protrusion) near2 (heat near (sink spreader	USPAT;	2004/05/14 15:09
40	390	dissipat\$6))	US-PGPUB	2007/00/17 15:09
<u></u>	L	1 2/FO/FO PM Page 1	1 00 1 01 00	L

Search History 5/14/04 3:59:59 PM Page 1

41	101	((bump\$5 ball protrusion) near2 (heat near (sink spreader	USPAT;	2004/05/14 15:10
11	101	dissipat\$6))) and ((flip ic circuit semiconductor) adj (chip die	US-PGPUB	
		dice)) same ((substrate carrier module) with (pad contact		
		electrode ubm underbump))		
43	247	(bump\$5 ball protrusion) near2 (heat near (sink spreader	EPO; JPO;	2004/05/14 15:09
	- "	dissipat\$6))	DERWENT;	, ,
		4.00,F4.4.5//	IBM_TDB	
44	19	((bump\$5 ball protrusion) near2 (heat near (sink spreader	EPO; JPO;	2004/05/14 15:10
••		dissipat\$6))) and ((flip ic circuit semiconductor) adj (chip die	DERWENT;	
		dice)) same ((substrate carrier module) with (pad contact	IBM_TDB	
		electrode ubm underbump))	_	
39	23	1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1	USPAT;	2004/05/14 15:13
"		dissipat\$6))) same ((flip ic circuit semiconductor) adj (chip	US-PGPUB	
		die dice)) same ((substrate carrier module) with (pad		
		contact electrode ubm underbump))		
42	46	1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1	USPAT;	2004/05/14 15:17
		438/612.ccls. 438/613.ccls. 438/615.ccls.) and ((bump\$5	US-PGPUB	
		ball protrusion) near2 (heat near (sink spreader		
		dissipat\$6)))		
-	13		USPAT;	2004/05/14 10:28
		20020180023.pn. 4034468.pn. 6437240.pn. 6396669.pn.	US-PGPUB	
	İ	6495915.pn. 6255143.pn. 6362530.pn. 6479903.pn.		
		6245186.pn. 6339254.pn.		